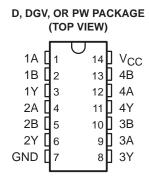
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- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Small-Outline (D), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages



description

This quadruple 2-input positive-NAND gate is designed for 1.65-V to 3.6-V V_{CC} operation.

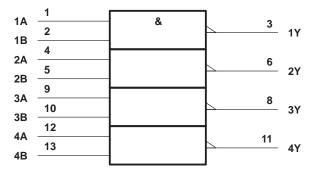
The SN74ALVC00 performs the Boolean function $Y = \overline{A \bullet B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The SN74ALVC00 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Υ
Н	Н	L
L	X	Н
Х	L	Н

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram, each gate (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		V to 4.6 V
Input voltage range, V _I (see Note 1)		V to 4.6 V
Output voltage range, VO (see Notes 1 and 2)	–0.5 V to V _C	C + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	-	. –50 mA
Output clamp current, I _{OK} (V _O < 0)		. –50 mA
Continuous output current, IO		. ±50 mA
Continuous current through V _{CC} or GND		$\pm 100 \; mA$
Package thermal impedance, θ_{JA} (see Note 3): D p	ackage	127°C/W
DG	V package	182°C/W
PW	/ package	170°C/W
Storage temperature range, Total		to 150°C

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 4.6 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
Vcc	Supply voltage		1.65	3.6	V	
VIH		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V _{CC}			
	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
	Low-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		0.35 × V _{CC}		
\vee_{IL}		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		
٧ _I	Input voltage	·	0	Vcc	V	
٧o	Output voltage		0	VCC	V	
	High-level output current	V _{CC} = 1.65 V		-4		
		V _{CC} = 2.3 V		-12	m ^	
ЮН		$V_{CC} = 2.7 \text{ V}$		-12	mA	
		V _{CC} = 3 V		-24		
		V _{CC} = 1.65 V		4		
1	Low-level output current	V _{CC} = 2.3 V		12	A	
lOL		$V_{CC} = 2.7 \text{ V}$		12	mA	
	V _{CC} = 3 V			24		
Δt/Δν	Input transition rise or fall rate		0	5	ns/V	
TA	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		VCC	MIN	TYP†	MAX	UNIT
	I _{OH} = -100 μA		1.65 V to 3.6 V	V _{CC} -0.	2		
	$I_{OH} = -4 \text{ mA}$		1.65 V	1.2			
	I _{OH} = -6 mA		2.3 V	2			
Voн			2.3 V	1.7			V
	$I_{OH} = -12 \text{ mA}$		2.7 V	2.2			
			3 V	2.4			
	I _{OH} = -24 mA	3 V	2				
	I _{OL} = 100 μA	1.65 V to 3.6 V			0.2		
	I _{OL} = 4 mA		1.65 V			0.45	
VoL	I _{OL} = 6 mA		2.3 V			0.4	V
VOL VOL	I _{OL} = 12 mA	2.3 V			0.7	V	
	IOL = 12 IIIA		2.7 V			0.4	
	I _{OL} = 24 mA		3 V			0.55	
ΙĮ	$V_I = V_{CC}$ or GND		3.6 V			±5	μΑ
Icc	$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			10	μΑ
ΔlCC	One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μΑ
C _i	$V_I = V_{CC}$ or GND		3.3 V		4.5		pF

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

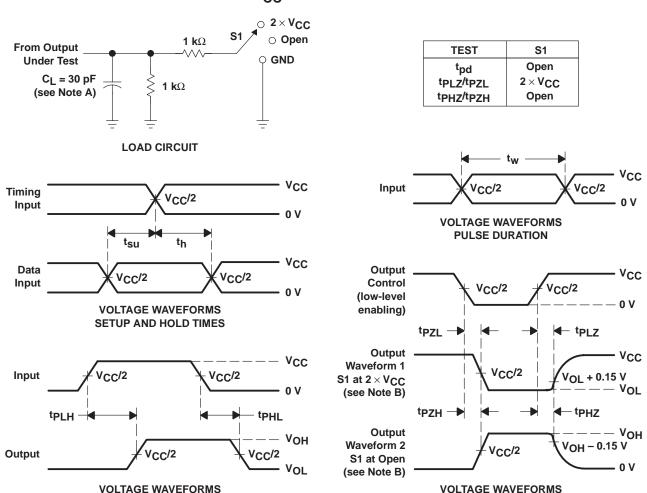
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM TO (INPUT)		V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
	(61)	(0011 01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
^t pd	A or B	Υ	1	4.4	1	2.8		3.2	1	3	ns

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS		V _{CC} = 1.8 V ± 0.15 V	V _{CC} = 2.5 V ± 0.2 V	V _{CC} = 3.3 V ± 0.3 V	UNIT
				TYP	TYP	TYP	
C _{pd}	Power dissipation capacitance per gate	$C_{L} = 0$,	f = 10 MHz	20	21	23	pF

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$



NOTES: A. C_L includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

ENABLE AND DISABLE TIMES

- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq$ 2 ns. $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.

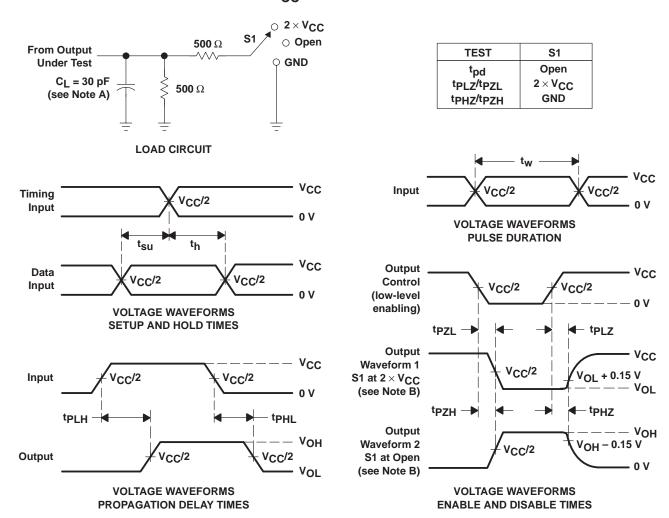
PROPAGATION DELAY TIMES

- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$

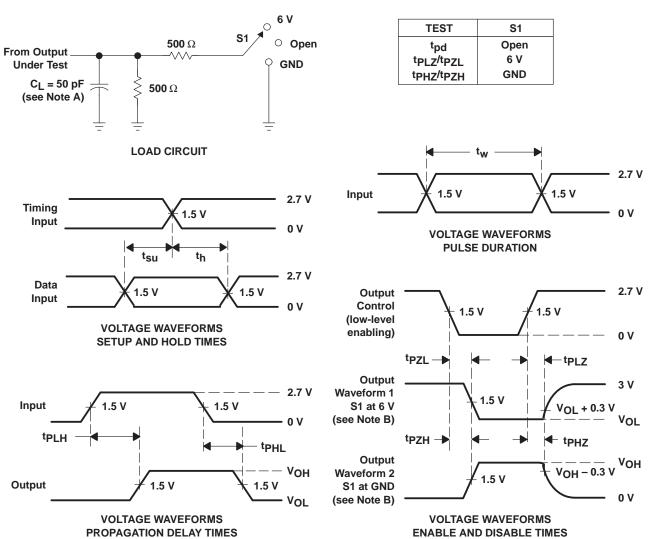


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2 ns. $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms



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